

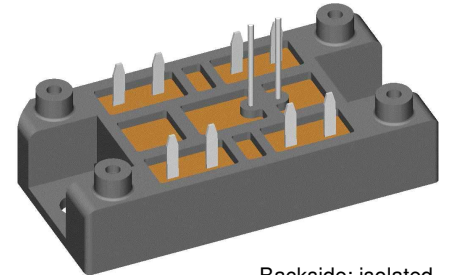
# Standard Rectifier Module

3~ Rectifier	Brake Chopper
$V_{RRM} = 1600 \text{ V}$	$V_{CES} = 1200 \text{ V}$
$I_{DAV} = 75 \text{ A}$	$I_{C25} = 58 \text{ A}$
$I_{FSM} = 600 \text{ A}$	$V_{CE(sat)} = 1.85 \text{ V}$

## 3~ Rectifier Bridge + Brake Unit

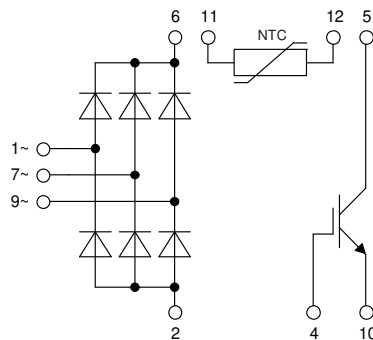
Part number

**VUI72-16NOXT**



Backside: isolated

E72873



### Features / Advantages:

- Package with DCB ceramic base plate
- Improved temperature and power cycling
- Planar passivated chips
- Very low forward voltage drop
- Very low leakage current
- NTC

### Applications:

- 3~ Rectifier with brake unit for drive inverters

### Package: V1-A-Pack

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Height: 17 mm
- Base plate: DCB ceramic
- Reduced weight
- Advanced power cycling

### Terms and Conditions of Usage

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact your local sales office.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact your local sales office.

Should you intend to use the product in aviation, in health or life endangering or life support applications, please notify. For any such application we urgently recommend

- to perform joint risk and quality assessments;

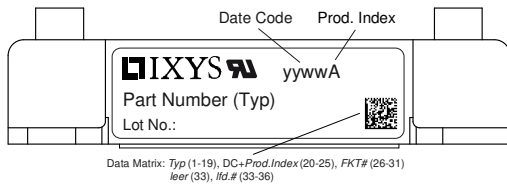
- the conclusion of quality agreements;

- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

Rectifier				Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit
$V_{RSM}$	max. non-repetitive reverse blocking voltage					1700	V
$V_{RRM}$	max. repetitive reverse blocking voltage					1600	V
$I_R$	reverse current	$V_R = 1600$ V		$T_{VJ} = 25^\circ\text{C}$		40	$\mu\text{A}$
		$V_R = 1600$ V		$T_{VJ} = 150^\circ\text{C}$		1.5	mA
$V_F$	forward voltage drop	$I_F = 25$ A		$T_{VJ} = 25^\circ\text{C}$		1.10	V
		$I_F = 75$ A				1.38	V
		$I_F = 25$ A		$T_{VJ} = 125^\circ\text{C}$		1.01	V
		$I_F = 75$ A				1.37	V
$I_{DAV}$	bridge output current	$T_C = 110^\circ\text{C}$	rectangular	$T_{VJ} = 150^\circ\text{C}$		75	A
$V_{FO}$	threshold voltage	} for power loss calculation only		$T_{VJ} = 150^\circ\text{C}$		0.79	V
$r_F$	slope resistance					7.7	m $\Omega$
$R_{thJC}$	thermal resistance junction to case					1.1	K/W
$R_{thCH}$	thermal resistance case to heatsink				0.3		K/W
$P_{tot}$	total power dissipation			$T_C = 25^\circ\text{C}$		110	W
$I_{FSM}$	max. forward surge current	$t = 10$ ms; (50 Hz), sine		$T_{VJ} = 45^\circ\text{C}$		600	A
		$t = 8,3$ ms; (60 Hz), sine		$V_R = 0$ V		650	A
		$t = 10$ ms; (50 Hz), sine		$T_{VJ} = 150^\circ\text{C}$		510	A
		$t = 8,3$ ms; (60 Hz), sine		$V_R = 0$ V		550	A
$I^2t$	value for fusing	$t = 10$ ms; (50 Hz), sine		$T_{VJ} = 45^\circ\text{C}$		1.80	kA <sup>2</sup> s
		$t = 8,3$ ms; (60 Hz), sine		$V_R = 0$ V		1.76	kA <sup>2</sup> s
		$t = 10$ ms; (50 Hz), sine		$T_{VJ} = 150^\circ\text{C}$		1.30	kA <sup>2</sup> s
		$t = 8,3$ ms; (60 Hz), sine		$V_R = 0$ V		1.26	kA <sup>2</sup> s
$C_J$	junction capacitance	$V_R = 400$ V; $f = 1$ MHz		$T_{VJ} = 25^\circ\text{C}$		19	pF

Brake IGBT + Diode				Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit	
$V_{CES}$	collector emitter voltage	$T_{VJ} = 25^{\circ}\text{C}$			1200	V	
$V_{GES}$	max. DC gate voltage				$\pm 20$	V	
$V_{GEM}$	max. transient gate emitter voltage				$\pm 30$	V	
$I_{C25}$	collector current	$T_C = 25^{\circ}\text{C}$			58	A	
$I_{C80}$		$T_C = 80^{\circ}\text{C}$			40	A	
$P_{tot}$	total power dissipation	$T_C = 25^{\circ}\text{C}$			195	W	
$V_{CE(sat)}$	collector emitter saturation voltage	$I_C = 35\text{ A}; V_{GE} = 15\text{ V}$			1.85	V	
					2.15	V	
$V_{GE(th)}$	gate emitter threshold voltage	$I_C = 2\text{ mA}; V_{GE} = V_{CE}$	5.4	5.9	6.5	V	
$I_{CES}$	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0\text{ V}$			0.1	mA	
					0.1	mA	
$I_{GES}$	gate emitter leakage current	$V_{GE} = \pm 20\text{ V}$			500	nA	
$Q_{G(on)}$	total gate charge	$V_{CE} = 600\text{ V}; V_{GE} = 15\text{ V}; I_C = 35\text{ A}$		110		nC	
$t_{d(on)}$	turn-on delay time	inductive load $V_{CE} = 600\text{ V}; I_C = 35\text{ A}$ $V_{GE} = \pm 15\text{ V}; R_G = 27\ \Omega$		70		ns	
$t_r$	current rise time			40		ns	
$t_{d(off)}$	turn-off delay time			250		ns	
$t_f$	current fall time			100		ns	
$E_{on}$	turn-on energy per pulse			3.8		mJ	
$E_{off}$	turn-off energy per pulse			4.1		mJ	
<b>RBSOA</b>	reverse bias safe operating area	$V_{GE} = \pm 15\text{ V}; R_G = 27\ \Omega$					
$I_{CM}$		$V_{CEK} = 1200\text{ V}$			105	A	
<b>SCSOA</b>	short circuit safe operating area	$V_{CEK} = 1200\text{ V}$					
$t_{SC}$	short circuit duration	$V_{CE} = 900\text{ V}; V_{GE} = \pm 15\text{ V}$			10	$\mu\text{s}$	
$I_{SC}$	short circuit current	$R_G = 27\ \Omega$ ; non-repetitive		140		A	
$R_{thJC}$	thermal resistance junction to case				0.65	K/W	
$R_{thCH}$	thermal resistance case to heatsink			0.25		K/W	

Package V1-A-Pack				Ratings		
Symbol	Definition	Conditions	min.	typ.	max.	Unit
$I_{RMS}$	RMS current	per terminal			100	A
$T_{VJ}$	virtual junction temperature		-40		150	°C
$T_{op}$	operation temperature		-40		125	°C
$T_{stg}$	storage temperature		-40		125	°C
<b>Weight</b>					37	g
$M_D$	mounting torque		2		2.5	Nm
$d_{Spp/App}$	creepage distance on surface / striking distance through air	terminal to terminal	6.0			mm
$d_{Spb/Apb}$		terminal to backside	12.0			mm
$V_{ISOL}$	isolation voltage	t = 1 second	3600			V
		t = 1 minute	3000			V



Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	VUI72-16NOXT	VUI72-16NOXT	Blister	24	510748

### Temperature Sensor NTC

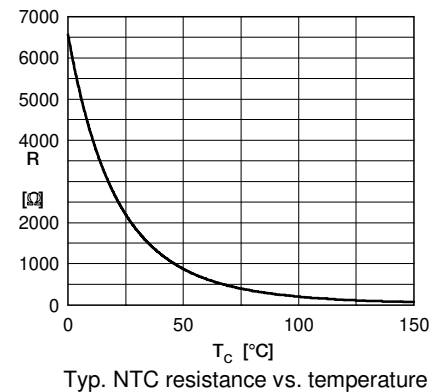
Symbol	Definition	Conditions	min.	typ.	max.	Unit
$R_{25}$	resistance	$T_{VJ} = 25^\circ$	2.13	2.2	2.27	k $\Omega$
$B_{25/50}$	temperature coefficient			3560		K

### Equivalent Circuits for Simulation

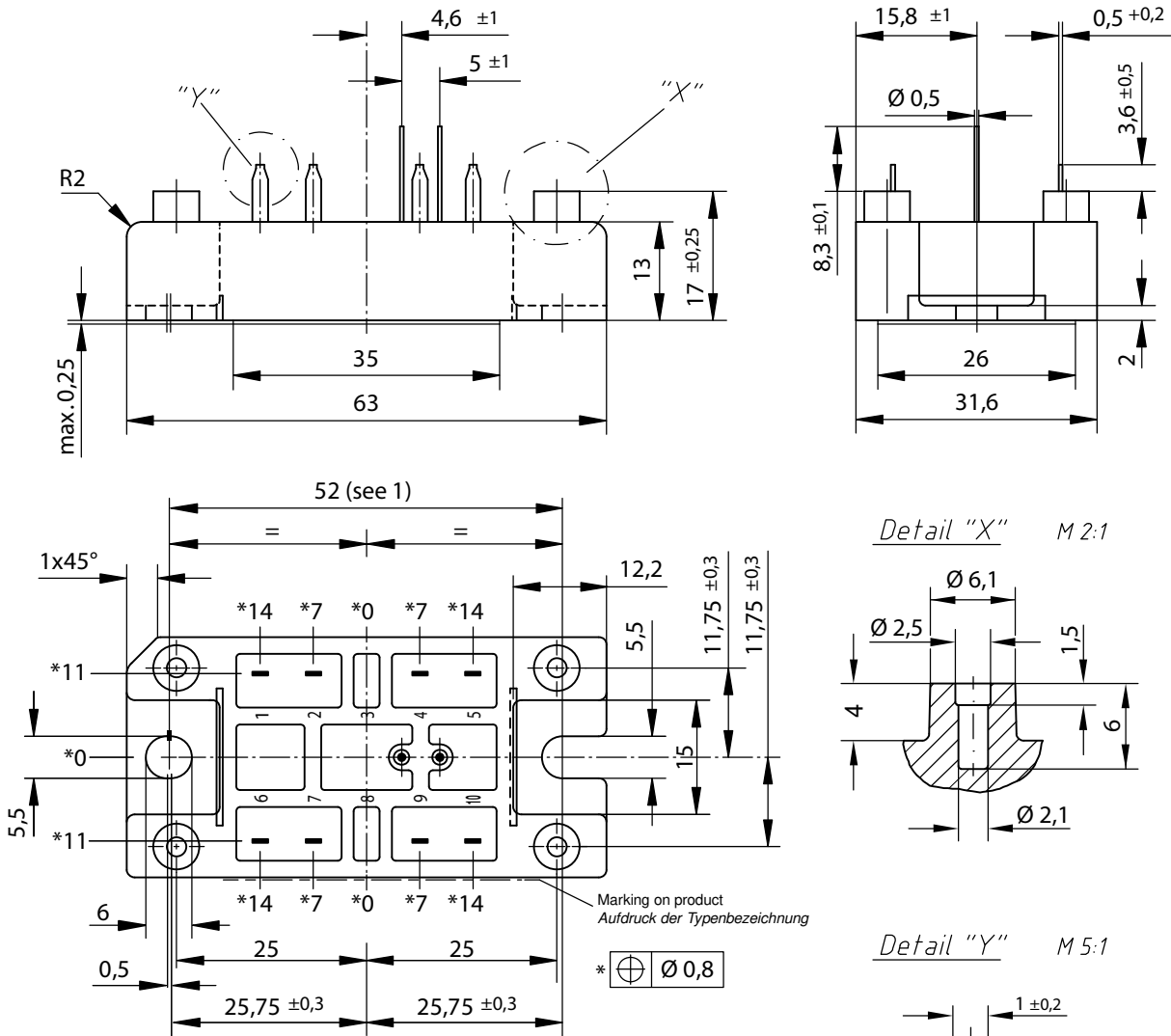
\* on die level

$T_{VJ} = 150^\circ\text{C}$

Symbol	Definition	Rectifier	Brake IGBT +	Unit
$V_0$	threshold voltage	0.79	1.1	V
$R_0$	slope resistance *	6.5	40	m $\Omega$

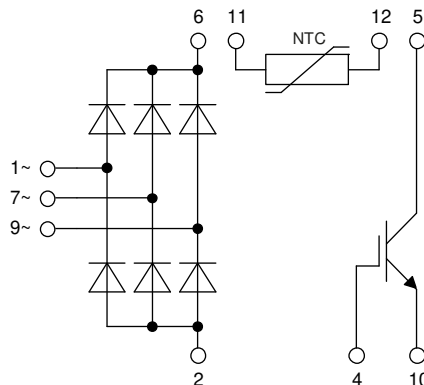


## Outlines V1-A-Pack



### Remarks / Bemerkungen:

- Nominal distance mounting screws on heat sink: 52 mm / Nennabstand Befestigungsschrauben auf Kühlkörper: 52 mm
- General tolerance / Allgmeintoleranz: DIN ISO 2768 - T1-c
- Surface treatment of pins: tin plated (Sn) in hot dip / Oberflächenbehandlung der Pins: verzinkt (Sn) im Tauchbad
- Detail X: <sup>L</sup>  
EJOT PT® self-tapping screws (dimension K25) to be recommended for mounting on PCB <sup>L</sup>  
selbstschneidende Schraube (Größe K25) empfohlen für die PCB-Montage  
Take care on the maximum screw length according to board thickness and the maximum hole depth of 6 mm<sup>L</sup>  
Bei der Wahl der Schraubenlänge die PCB-Dicke und die maximale Lochtiefe von 6mm beachten  
Recommended mounting torque: 1.5 Nm / Empfohlenes Drehmoment: 1.5 Nm



**Rectifier**

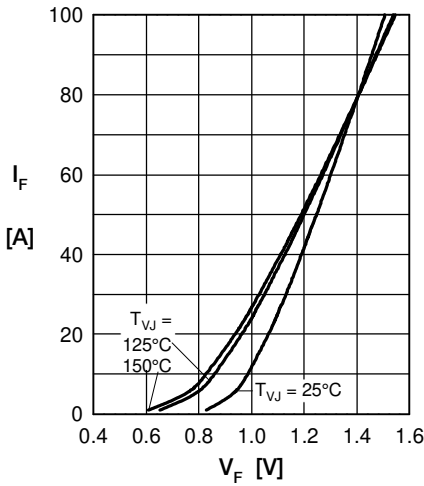


Fig. 1 Forward current vs. voltage drop per diode

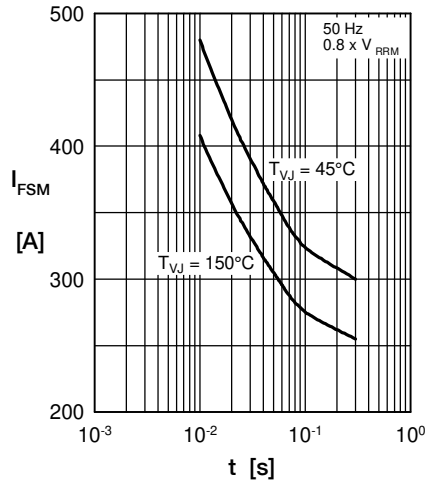


Fig. 2 Surge overload current vs. time per diode

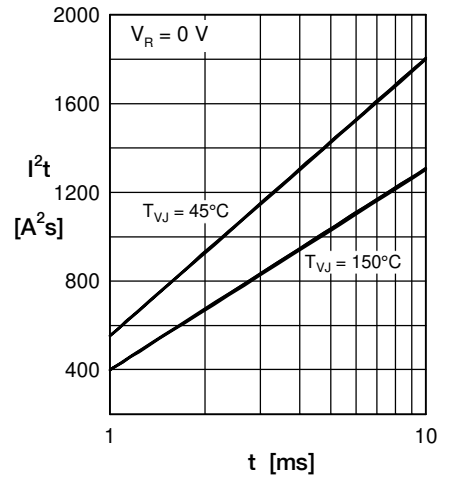


Fig. 3  $I^2t$  vs. time per diode

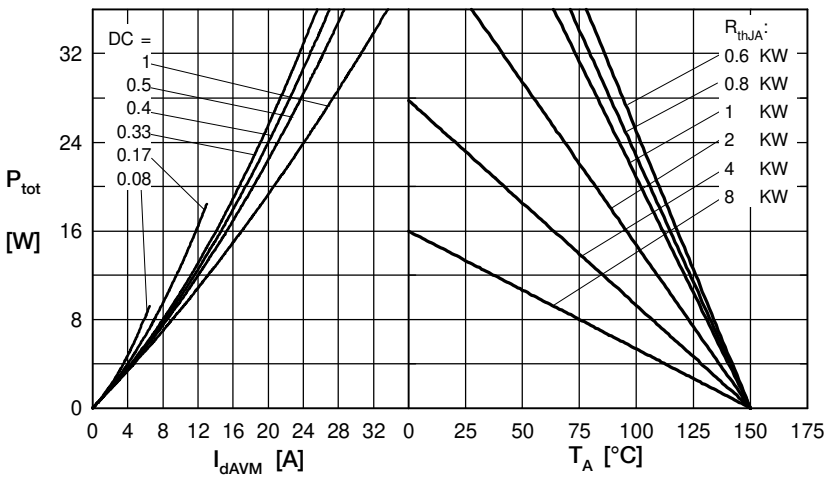


Fig. 4 Power dissipation vs. forward current and ambient temperature per diode

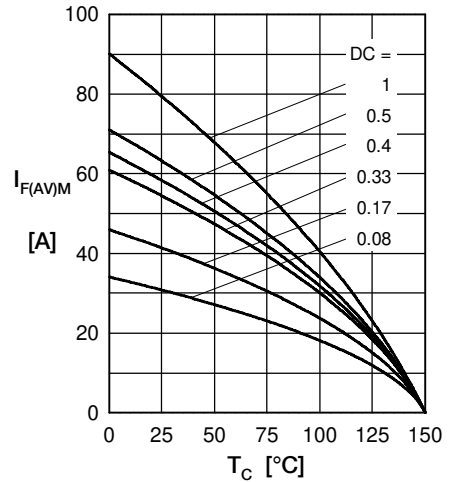


Fig. 5 Max. forward current vs. case temperature per diode

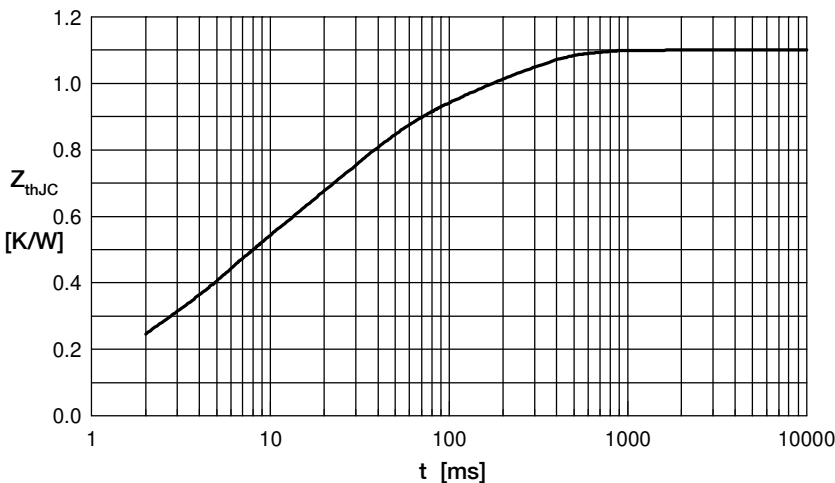


Fig. 6 Transient thermal impedance junction to case vs. time per diode

Constants for  $Z_{thJC}$  calculation:

i	$R_{th}$ (K/W)	$t_i$ (s)
1	0.0607	0.0004
2	0.1230	0.00256
3	0.2305	0.0045
4	0.4230	0.0242
5	0.2628	0.1800

**Brake IGBT + Diode**

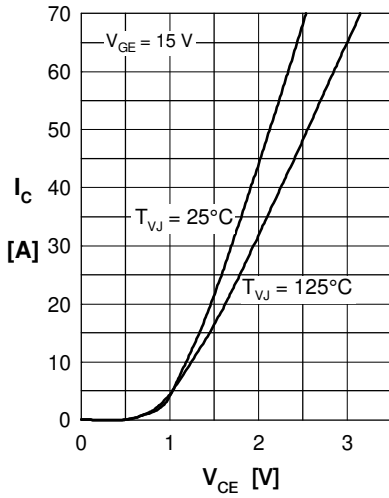


Fig. 1 Typ. output characteristics

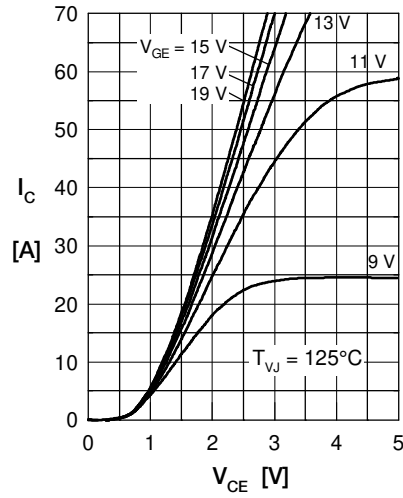


Fig. 2 Typ. output characteristics

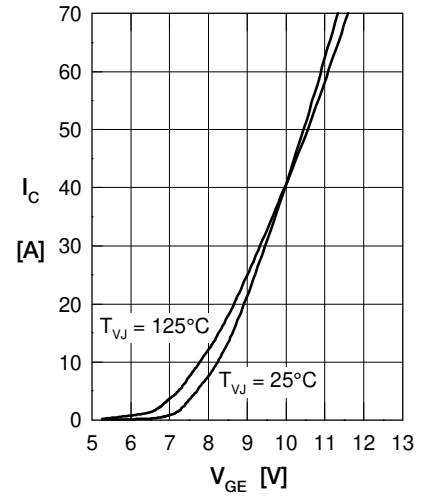


Fig. 3 Typ. transfer characteristics

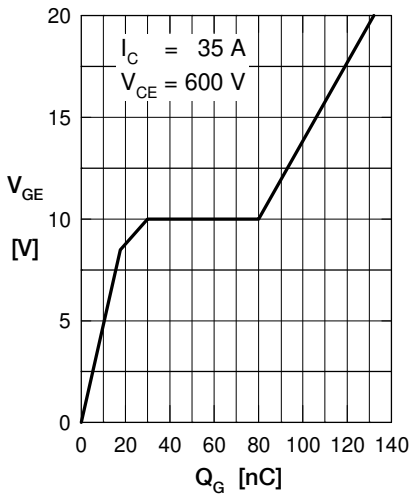


Fig. 4 Typ. turn-on gate charge

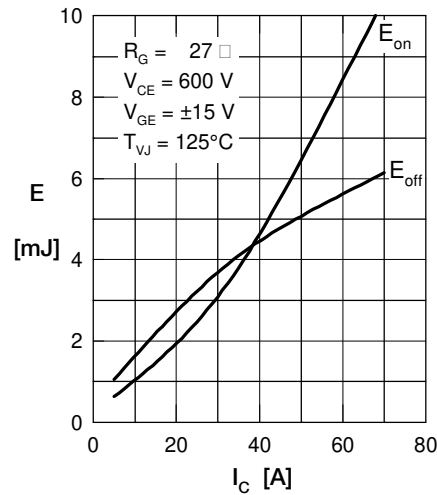


Fig. 5 Typ. switching energy versus collector current

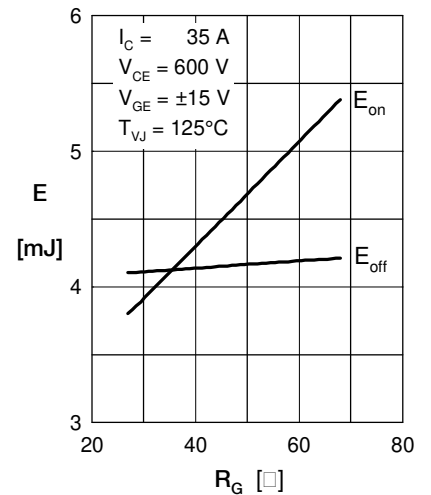


Fig. 6 Typ. switching energy versus gate resistance

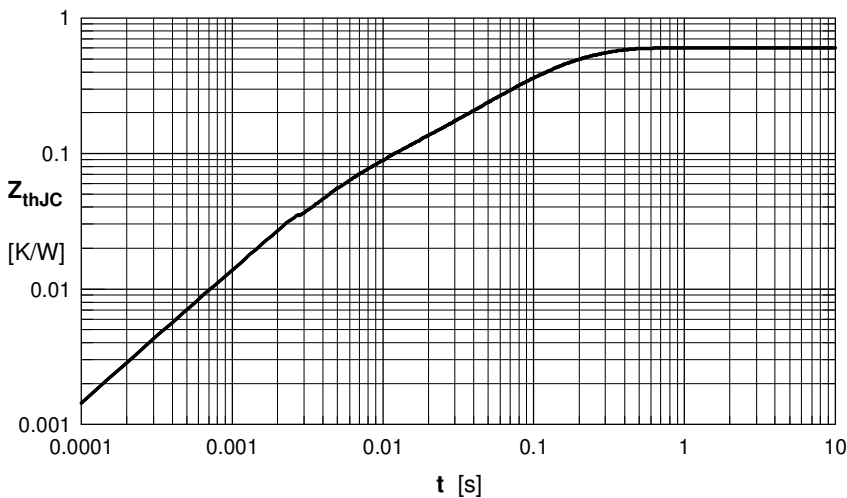


Fig. 7 Typ. transient thermal impedance